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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon
Title: METHOD OF PACKAGING AT A WAFER LEVEL

Docket No.: 303.601US3
Filed: November 26, 2003
Examiner: James M. Mitchell

Serial No.: 10/722,838
Due Date: December 20, 2006
Group Art Unit: 2813

MS Amendment


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

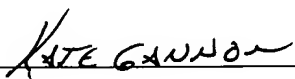
- ☒ Return postcard.
- ☒ Amendment and Response (9 pgs.).
- ☒ Communication Concerning Related Applications (2 pgs.).
- ☒ Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.).
- ☒ Authorization to charge Deposit Account 19-0743 in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

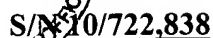
By: 
Atty: David R. Cochran
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 20 day of December, 2006.


Name


Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



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<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09505018 6710454	February 16, 2000	303.601US1	AN ADHESIVE LAYER FOR AN ELECTRONIC APPARATUS HAVING MULTIPLE SEMICONDUCTOR DEVICES
11460089	July 26, 2006	303.601US4	WAFER LEVEL PRE-PACKAGED FLIP CHIP
11460093	July 26, 2006	303.601US5	WAFER LEVEL PRE-PACKAGED FLIP CHIP
11460435	July 27, 2006	303.601US6	WAFER LEVEL PRE-PACKAGED FLIP CHIP SYSTEMS
11460445	July 27, 2006	303.601US7	WAFER LEVEL PRE-PACKAGED FLIP CHIP SYSTEM

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request


that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

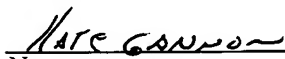
SUAN J. BOON

By Applicant's Representatives,

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Date 20 December 2004 By 
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Reg. No. 46,632

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